

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2756#4
2152

In re Patent Application of:

SHIMADA, N.

Serial No.: 09/506,215

Filed: 2/17/00

For: NODE CAPABLE OF SAVING A THIRD-LAYER ...



Our Ref.: P/126-182

Date: August 9, 2001

Group Art Unit: 2756

Examiner: --

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Assistant Commissioner of Patents

Washington, D.C. 20231

Technology Center 2100

SUBMISSION

Sir:

<input checked="" type="checkbox"/>	Submitted herewith is a copy of art together with an art listing form listing the same for the convenience of the Examiner.
<input type="checkbox"/>	The document(s) listed on the attached art listing form was/were cited in a Search Report issued by a foreign patent office in a related application. A copy of the Search Report (in the English language) is attached hereto for the Examiner's reference.
<input checked="" type="checkbox"/>	The Japanese Publication(s) listed on the attached art listing form was/were cited in a Japanese Office Action issued June 20, 2001 in a related application. A copy of the Japanese Office Action and an English-language translation of the relevant portions are also attached. SEE ENGLISH-TRANSLATION FOR NON-ENGLISH-LANGUAGE DOCUMENTS.
<input type="checkbox"/>	This submission is being made after the issuance of a first Office Action and three months after the application filing date. Thus a Certification Under 37 C.F.R. §1.97(e) is set forth below.
<input checked="" type="checkbox"/>	I hereby certify that each item of information contained in this Submission was cited in a communication from a foreign patent office in a counterpart foreign application not more than three (3) months prior to the filing of this Submission (37 C.F.R. §1.97(e)).
<input type="checkbox"/>	This submission is being made after the issuance of the first Office Action and without a certification. The fee of \$180.00 under 37 C.F.R. §1.17(p) is attached.
<input type="checkbox"/>	This submission is being made after the issuance of a final rejection or a Notice of Allowance but prior to the payment of the issue fee. Applicant(s) hereby attach the fee of \$180.00 under 37 C.F.R. §1.17(I). A certification under 37 C.F.R. §1.97(e) is set forth above.

CERTIFICATE OF MAILING

Respectfully submitted,

I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington,
D.C. 20231-9999, on August 9, 2001:

Steven I. Weisburd

Name of applicant, assignee or
Registered Representative

Signature

August 9, 2001

Date of Signature

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Claims 1 through 20

Publication:

1. Yuhei Iwasaki, "New LAN Introduction Method 9, Layer 3 Switch Construction," Computer & Network LAN, Vol. 16, No. 6, Ohm Company, Limited, pp. 87-90, June 1998.

Claims 1 through 20

Cited Example 1

Cited Example 1 describes the fact that, in a transmission device that has a cut-through function, whether the packet is to be hopped at the next node or dropped at that node is not decided by the router but by the ATM switch, thereby dropping only the packet that should be dropped at that node, with the other packets being cut-through.

Accordingly, the inventions pertaining to Claims 1 through 20 of this application are such as could be conceived of easily by the people in the industry on the basis of what is described in Cited Example 1.

Record of the Result of a Survey on Prior Technical Literature.

Fields Covered in the Survey:

IPC Seventh Edition H 04 L 12/56

H 04 J 3/00

Prior Technical Literature:

1. Hiroshi Esaki: "High Speed Routing Technique and Multi-layer Switch Technique," bit Vol. 30, No. 5, Kyoritsu Publishing Company, Limited, pp. 83-91, May 1998

2. Yuhei Iwasaki, "New LAN Introduction Method 11, Cut-through Layer 3 Switch Construction," Computer & Network LAN, Vol. 16, No. 9, Ohm Publishing Company, Limited, pp. 57-61, September 1998.